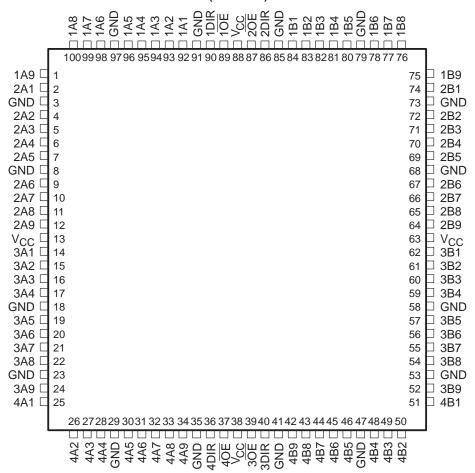
- Members of the Texas Instruments
  Widebus+™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  < 0.8 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Impedance State During Power Up and Power Down
- Released as DSCC SMD 5962-9557701NXD
- PZ Package Qualified for Military Per MIL-PRF-38535 (QML)

- Distributed V<sub>CC</sub> and GND Pin Configuration Minimizes High-Speed Switching Noise
- High-Drive Outputs (–32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include 100-Pin Plastic Thin Quad Flat (PZ) Package With 14 × 14-mm Body Using 0.5-mm Lead Pitch and Space-Saving 100-Pin Ceramic Quad Flat (HS) Package<sup>†</sup>

## 'ABTH32245 . . . PZ PACKAGE (TOP VIEW)



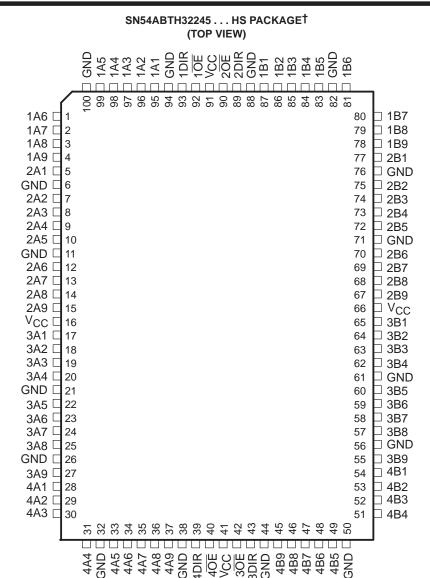
† The HS package is not production released.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus+ and EPIC-IIB are trademarks of Texas Instruments Incorporated.





† For HS package availability, please contact the factory or your local TI Field Sales Office.

### description

The 'ABTH32245 are 36-bit (quad 9-bit) noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as four 9-bit transceivers, two18-bit transceivers, or one 36-bit transceiver. They allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) inputs. The output-enable  $(\overline{OE})$  inputs can be used to disable the device so that the buses are effectively isolated.

When  $V_{CC}$  is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or floating data inputs at a valid logic level.



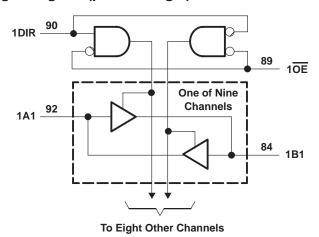
### description (continued)

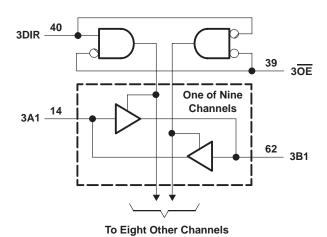
The SN54ABTH32245 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABTH32245 is characterized for operation from –40°C to 85°C.

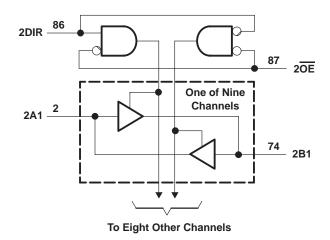
FUNCTION TABLE (each 9-bit section)

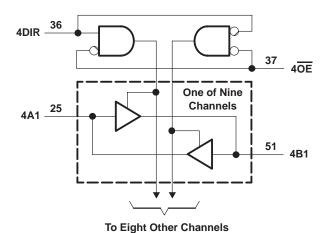
INP	UTS	ODEDATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	X	Isolation

### logic diagram (positive logic)









Pin numbers shown are for the PZ package.

### SN54ABTH32245, SN74ABTH32245 36-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS228G - JUNE 1992 - REVISED MAY 1997

### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	
Voltage range applied to any output in the high or power-off state, V <sub>O</sub>	
Current into any output in the low state, IO: SN54ABTH32245	96 mA
SN74ABTH32245	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): PZ package	50°C/W
Storage temperature range, T <sub>stq</sub>	-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

					SN74ABTH32245		UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	V <sub>CC</sub> Supply voltage				4.5	5.5	V
VIH	High-level input voltage		2		2		V
V <sub>IL</sub>	V <sub>IL</sub> Low-level input voltage					0.8	V
VI	Input voltage	0	Vcc	0	VCC	V	
loн	I <sub>OH</sub> High-level output current					-32	mA
l <sub>OL</sub>	Low-level output current					64	mA
Δt/Δν	Input transition rise or fall rate Outputs enabled			10		10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate	200	·	200		μs/V	
TA	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 3: Unused control pins must be held high or low to prevent them from floating.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			SN54ABTH32245			SN74ABTH32245			
PAI	TANAMETER TEST CONDITIONS		DITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	I <sub>I</sub> = -18 mA			-1.2			-1.2	V	
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5				
\/a	V <sub>CC</sub> = 5 V,		$I_{OH} = -3 \text{ mA}$	3			3			V	
VOH		V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$	2						V	
		VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$				2				
VOL		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 48 mA			0.55			0.55	V	
VOL		VCC = 4.5 V	I <sub>OL</sub> = 64 mA						0.55	V	
V <sub>hys</sub>					100			100		mV	
	Control inputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND						±1		
1.	A or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND						±20	μΑ	
li .	Control inputs	VCC = 5.5 V,	V <sub>I</sub> = V <sub>CC</sub> or GND			±1				μΑ	
	A or B ports	VCC = 5.5 V,	AL = ACC OLGIAD			±20				μΑ	
ha in	I <sub>I(hold)</sub> A or B ports	V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 0.8 V	100			100			μА	
'I(hold)		VCC = 4.5 V	V <sub>I</sub> = 2 V	-100			-100				
lozpu <sup>‡</sup>		$V_{CC} = 0$ to 2.1 V, $V_{O} = 0.5$	V to 2.7 V, $\overline{OE} = X$			±50			±50	μΑ	
lozpd <sup>‡</sup>		$V_{CC} = 2.1 \text{ V to } 0, V_{O} = 0.5$	V to 2.7 V, $\overline{OE} = X$			±50			±50	μΑ	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 V$						±100	μΑ	
ICEX		$V_{CC} = 5.5 \text{ V}, V_{O} = 5.5 \text{ V}$	Outputs high			50			50	μΑ	
ΙΟ§		$V_{CC} = 5.5 \text{ V},$	V <sub>O</sub> = 2.5 V	-50	-100	-180	-50	-100	-180	mA	
		V <sub>CC</sub> = 5.5 V,	Outputs high			3			3		
ICC	Icc	$I_{O} = 0$ ,	Outputs low			20			20	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2			2		
ΔICC¶		$V_{CC} = 5.5 \text{ V}$ , One input at 3 Other inputs at $V_{CC}$ or GNI				1			1	mA	
Ci	Control inputs	V <sub>I</sub> = 2.5 V or 0.5 V			3.5			3.5		pF	
C <sub>io</sub>	A or B ports	V <sub>O</sub> = 2.5 V or 0.5 V			9.5			9.5		рF	

 $<sup>\</sup>uparrow$  All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C#			SN54ABTH32245		SN74ABTH32245		UNIT
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A or B	B or A	1.7	3.2	4.4	1	5.3	1.7	5	
t <sub>PHL</sub>	AUD	BULA	1.7	3.3	4.6	1	5.3	1.7	5.2	ns
<sup>t</sup> PZH	<del></del>	P.or A	1.6	4.2	6.1	1	7.6	1.6	7.3	
t <sub>PZL</sub>	ŌĒ	B or A	2.7	5.2	7	1.5	8.2	2.7	8.1	ns
t <sub>PHZ</sub>	ŌĒ	B or A	1.3	3.9	6.1	0.8	6.7	1.3	6.5	
tPLZ	OE	BULA	2	4.4	6.6	1	7.2	2	6.9	ns

<sup>#</sup>These limits apply only to the SN74ABTH32245

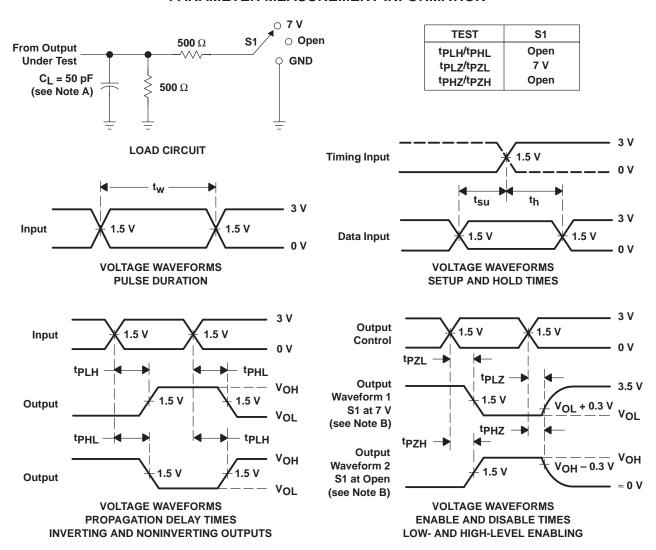


<sup>‡</sup> This parameter is specified by characterization.

<sup>§</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>¶</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50~\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







tom 18-Sep-2008

### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins I	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9557701NXD	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
SN74ABTH32245PZ	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR
SN74ABTH32245PZG4	ACTIVE	LQFP	PZ	100	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

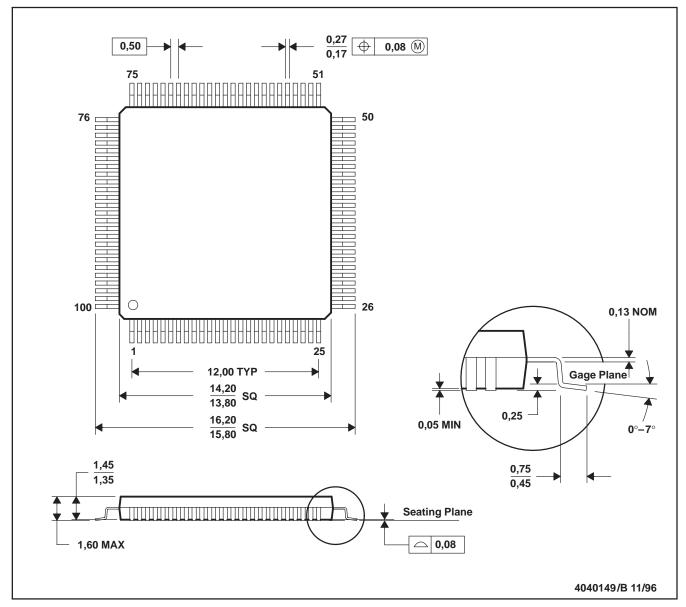
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

### PZ (S-PQFP-G100)

### PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Falls within JEDEC MS-026

### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

#### **Products Amplifiers** amplifier.ti.com Data Converters dataconverter.ti.com DSP dsp.ti.com Clocks and Timers www.ti.com/clocks Interface interface.ti.com Logic logic.ti.com Power Mamt power.ti.com Microcontrollers microcontroller.ti.com www.ti-rfid.com RF/IF and ZigBee® Solutions www.ti.com/lprf

www.ti.com/audio
www.ti.com/automotive
www.ti.com/broadband
www.ti.com/digitalcontrol
www.ti.com/medical
www.ti.com/military
www.ti.com/opticalnetwork
www.ti.com/security
www.ti.com/telephony
www.ti.com/video
www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2008, Texas Instruments Incorporated